

# NB3L83948C

## 2.5 V / 3.3 V Differential and LVTTTL/LVCMOS 2:1 MUX to 1:12 LVCMOS Fanout

### Description

The NB3L83948C is a pure 2.5 V / 3.3 V ( $V_{DD} = V_{DDO}$ ) or mixed mode 3.3 V Core ( $V_{DD}$ ) / 2.5 V Output ( $V_{DDO}$ ) clock distribution buffer with the capability to select either a differential LVPECL / LVDS / LVHSTL / SSTL / HCSL or single ended LVCMOS / LVTTTL compatible input clock, such as a Primary or a Test Clock. All other control inputs (CLK\_SEL, CLK\_EN, and OE) are LVTTTL/LVCMOS level compatible.

The NB3L83948C provides an enable input, CLK\_EN pin, which synchronously enables or disables the clock outputs while in the LOW state. Since this input is internally synchronized to the input clock, changing only when the input is LOW, potential output glitching or runt pulse generation is eliminated.

The 12 LVCMOS output pins drive 50  $\Omega$  series or parallel terminated transmission lines. The outputs can also be disabled to a high impedance (tri-stated) via the OE input, or enabled when High.

Fit, Form, and Function compatible with ICS83948I-147, ICS83948I-01, CY29948AXI, and MPC9448/9448L

### Features

- 2.5 V / 3.3V ( $V_{DD} = V_{DDO}$ ) or 3.3 V  $V_{DD}$  / 2.5 V  $V_{DDO}$  Operation:
  - 2.5  $\pm$  5%; 2.375 to 2.625 V
  - 3.3  $\pm$  5%; 3.135 to 3.465 V
- 350 MHz Clock Support
- Accepts LVPECL, LVDS, LVHSTL, SSTL, HCSL, or LVCMOS Clock Inputs
- LVCMOS Compatible Control Inputs
- 12 LVCMOS Clock Outputs
- Synchronous Clock Select
- Output Enable to High Z State Control
- 100 ps Max. Skew Between Outputs
- Industrial Temp. Range  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$
- 32-pin LQFP Package
- These are Pb-Free Devices



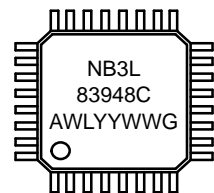
ON Semiconductor®

<http://onsemi.com>



LQFP-32  
FA SUFFIX  
CASE 873A

### MARKING DIAGRAMS\*



A = Assembly Location  
WL = Wafer Lot  
YY = Year  
WW = Work Week  
G = Pb-Free Package

(\*Note: Microdot may be in either location)

\*For additional marking information, refer to Application Note AND8002/D.

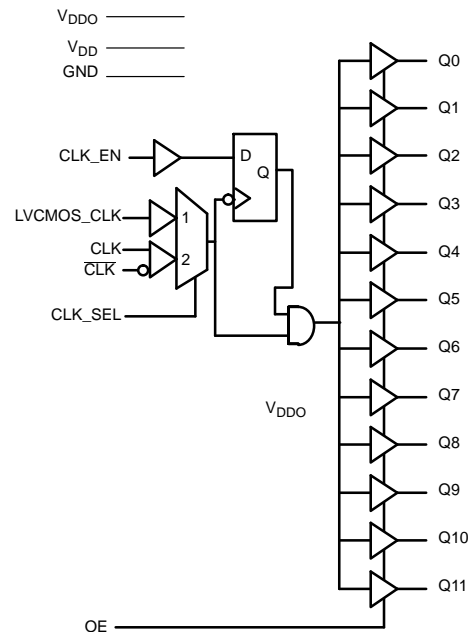


Figure 1. Simplified Logic Diagram

### ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

# NB3L83948C

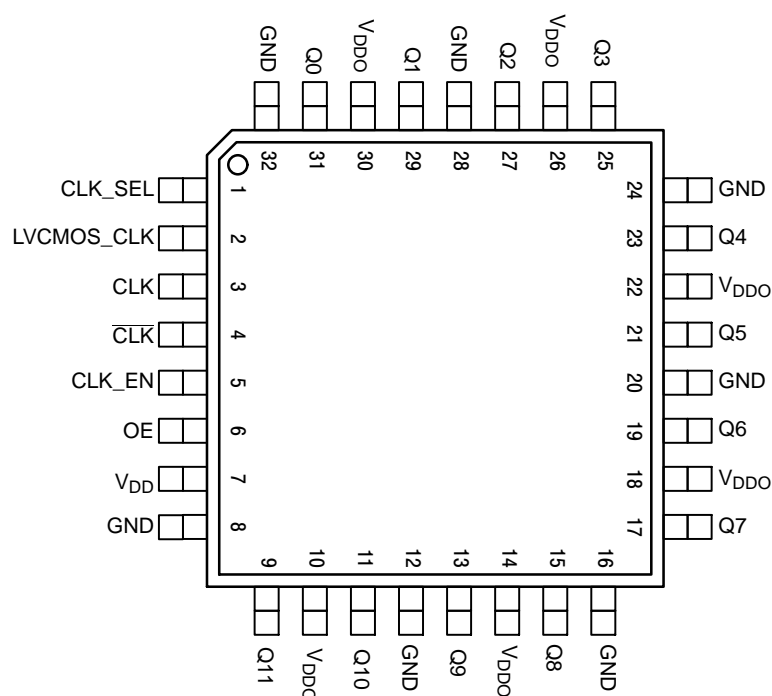


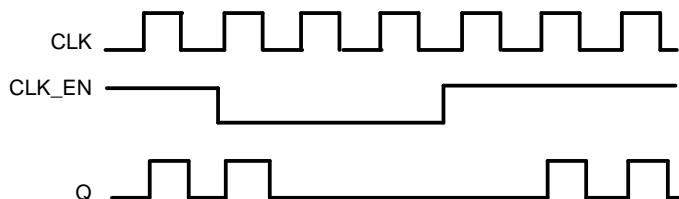
Figure 2. Pinout Configuration (Top View)

Table 1. PIN DESCRIPTION

Pin	Name	I/O	Open Default	Description
1	CLK_SEL	LVTTL/LVC MOS Input	Pullup	Clock Select Input. When LOW, the CLK/ $\overline{\text{CLK}}$ differential inputs are selected. When HIGH, LVC MOS_CLK is selected.
2	LVC MOS_CLK	LVTTL/LVC MOS Input	Pullup	Single ended Test Clock Input
3	CLK	LVPECL, LVDS, LVHSTL, SSTL, HC SL, or LVC MOS	Pullup	True Clock Input (internal)
4	$\overline{\text{CLK}}$	LVPECL, LVDS, LVHSTL, SSTL, HC SL, or LVC MOS	Pulldown	Invert Clock Input
5	CLK_EN	LVTTL/LVC MOS Input	Pullup	Synchronous Clock Enable Input. When HIGH, outputs are enabled. When LOW, outputs are disabled (LOW).
6	OE	LVTTL/LVC MOS Input	Pullup	Output High Z State control. When HIGH, the outputs are active and enabled. When LOW, the outputs are high impedance disabled.
7	V <sub>DD</sub>	POWER		V <sub>DD</sub> Positive Supply pin for core logic. All V <sub>DD</sub> , V <sub>DDO</sub> , and GND pins must be externally connected to a power supply to guarantee proper operation. Bypass with 0.01 $\mu\text{F}$ cap to GND.
8, 12, 16, 20, 24, 28, 32	GND	GND		GND Supply Ground. All V <sub>DD</sub> , V <sub>DDO</sub> and GND pins must be externally connected to power supply to guarantee proper operation.
9, 11, 13, 15, 17, 19, 21, 23, 25, 27, 29, 31	Q[11:0]	LVC MOS Output		Clock Output Pins
10, 14, 18, 22, 26, 30	V <sub>DDO</sub>	POWER		V <sub>DDO</sub> Positive Supply pins. All V <sub>DD</sub> , V <sub>DDO</sub> , and GND pins must be externally connected to a power supply to guarantee proper operation. Bypass each supply pin with 0.01 $\mu\text{F}$ to GND.

**Table 2. CLOCK SELECT FUNCTION TABLE**

Control Input	Clock	
CLK_SEL	CLK, $\overline{\text{CLK}}$	LVC MOS_CLK
0	Selected	De-Selected
1	De-Selected	Selected



**Figure 3. CLK\_EN Control Timing Diagram**

The CLK\_EN control input synchronously enables or disables the outputs as shown in Figure 3. This control latches on the falling edge of the selected input CLK. When CLK\_EN is LOW, the outputs are disabled in a LOW state. When CLK\_EN is HIGH, the outputs are enabled as shown. CLK\_EN to CLK Set up and Hold times must be satisfied.

**Table 3. ATTRIBUTES** (Note 1)

Characteristics	Value
Internal Input Pullup and Pulldown Resistor	50 kΩ
ESD Protection	Human Body Model Machine Model
	> 1.5 kV > 200 V
Moisture Sensitivity (Note 1)	Level 2
Flammability Rating Oxygen Index	UL-94 code V-0 A 1/8" 28 to 34
Transistor Count	275 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional information, see Application Note AND8003/D.

**Table 4. MAXIMUM RATINGS** (Note 2)

Symbol	Parameter	Condition	Rating	Unit
V <sub>DD</sub> /V <sub>DDO</sub>	Positive Power Supply	GND = 0 V	4.6	V
V <sub>I</sub>	Input Voltage		-0.3 ≤ V <sub>I</sub> ≤ V <sub>DD</sub> + 0.3	V
T <sub>A</sub>	Operating Temperature Range, Industrial		-40 to ≤ +85	°C
T <sub>stg</sub>	Storage Temperature Range		-65 to +150	°C
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	80 55	°C/W °C/W
θ <sub>JC</sub>	Thermal Resistance (Junction-to-Case)	(Note 3)	12-17	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and not valid simultaneously. If stress limits are exceeded device functional operation is not implied, damage may occur and reliability may be affected.
- JEDEC standard multilayer board – 2S2P (2 signal, 2 power).

## NB3L83948C

**Table 5. DC CHARACTERISTICS**  $V_{DD} = V_{DDO} = 3.3 \pm 5\%$  (3.135 to 3.465 V) or  $2.5 \pm 5\%$  (2.375 to 2.625 V);  $V_{DD} = 3.3 \pm 5\%$  (3.135 to 3.465 V) and  $V_{DDO} = 2.5 \pm 5\%$  (2.375 to 2.625 V)  $GND = 0\text{ V}$ ,  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ; (Note 4)

Symbol	Characteristic	Min	Typ	Max	Unit
$I_{DD}$	Quiescent Power Supply Current $3.3\text{ V } V_{DD} = V_{DDO}$ or $3.3\text{ V } V_{DD}, 2.5\text{ V } V_{DDO}$ $2.5\text{ V } V_{DD} = V_{DDO}$			55 52	mA
$V_{IH}$	Input HIGH Voltage at $3.465\text{ V } V_{DD}$ CLK_SEL; LVCMOS_CLK, CLK_EN, OE	2.0		$V_{DD}+0.3$	V
	Input HIGH Voltage $2.625\text{ V } V_{DD}$ CLK_SEL; LVCMOS_CLK, CLK_EN, OE	1.7		$V_{DD}+0.3$	V
$V_{IL}$	Input LOW Voltage $3.465\text{ V } V_{DD}$ CLK_SEL; LVCMOS_CLK, CLK_EN, OE	-0.3		0.8	V
	Input LOW Voltage $2.625\text{ V } V_{DD}$ CLK_SEL; LVCMOS_CLK, CLK_EN, OE	-0.3		0.7	V
$I_{IN}$	Input Current ( $V_{IN} = V_{DD}$ )			300	$\mu\text{A}$
$V_{OH}$	Output HIGH Voltage $I_{OH} = -24\text{ mA}$ $3.3\text{ V } \pm 5\% = V_{DD} = V_{DDO}$	2.4			V
	Output HIGH Voltage $I_{OH} = -15\text{ mA}$ $3.3\text{ V } \pm 5\%$ or $2.5\text{ V } \pm 5\% = V_{DD}$ ; $2.5\text{ V } +5\% = V_{DDO}$	1.8			V
$V_{OL}$	Output LOW Voltage $I_{OL} = 24\text{ mA}$ $3.3\text{ V } \pm 5\% = V_{DD} = V_{DDO}$			0.55	V
	Output LOW Voltage $I_{OL} = 12\text{ mA}$ $3.3\text{ V } \pm 5\% = V_{DD} = V_{DDO}$			0.3	V
	Output LOW Voltage $I_{OL} = 15\text{ mA}$ $0.3\text{ V } \pm 5\% = V_{DD}$ ; $2.5\text{ V } \pm 5\% = V_{DDO}$			0.6	V
$V_{CMR}$	Common Mode Voltage Range (CLK/ $\overline{\text{CLK}}$ ) $3.3\text{ V } \pm 5\%$ or $2.5\text{ V } \pm 5\% = V_{DD}$	GND+0.5		$V_{DD}-0.85$	V
$V_{PP}$	Input Voltage (Peak-to-Peak) CLK/ $\overline{\text{CLK}}$ $3.3\text{ V } \pm 5\%$ or $2.5\text{ V } \pm 5\% = V_{DD}$	0.15		1.3	V
$Z_O$	Output Impedance	5	7	12	$\Omega$
$C_{IN}$	Input Capacitance			4	pF
$C_{PD}$	Power Dissipation Capacitance (per Output)		25		pF

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

4. Parallel terminated  $50\ \Omega$  to  $V_{DDO}/2$ . See Figure 5.

# NB3L83948C

**Table 6. AC CHARACTERISTICS**  $V_{DD} = V_{DDO} = 3.3 \pm 5\%$  (3.135 to 3.465 V) or  $2.5 \pm 5\%$  (2.375 to 2.625 V);  $V_{DD} = 3.3 \pm 5\%$  (3.135 to 3.465 V) and  $V_{DDO} = 2.5 \pm 5\%$  (2.375 to 2.625 V)  $GND = 0\text{ V}$ ,  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ; (Note 5)

Symbol	Characteristic	Min	Typ	Max	Unit	
$F_{max}$	Maximum Operating Frequency	350			MHz	
$t_{PLH}/t_{PHL}$	Propagation Delay, (crosspoint to $V_{DDO}/2$ ) $f \leq 350\text{ MHz}$				ns	
	3.3 V $V_{DD} = V_{DDO}$ or 3.3 V $V_{DD}$ , 2.5 V $V_{DDO}$ ; CLK/ $\overline{\text{CLK}}$ to Qx	1.6		3.6	ns	
	3.3 V $V_{DD} = V_{DDO}$ or 3.3 V $V_{DD}$ , 2.5 V $V_{DDO}$ ; 3.3 V LVCMOS_CLK to Qx	1.0		3.0		
	2.5 V $V_{DD} = V_{DDO}$ CLK/ $\overline{\text{CLK}}$ to Qx	1.6		3.6		
2.5 V $V_{DD} = V_{DDO}$ LVCMOS_CLK to Qx	1.0		3.0			
$t_{PZL}/t_{PZH}$	Output Enable Time OE to Qx			5	ns	
$t_{PLZ}/t_{PHZ}$	Output Disable Time OE to Qx			5	ns	
$t_{SKEW_{DC}}$	Duty Cycle Skew at $V_{DD} / 2$				%	
		At 150 MHz; 3.3 V $V_{DD} = V_{DDO}$	45			55
		At 200 MHz; 2.5 V $V_{DD} = V_{DDO}$	45			55
		At 150 MHz; 2.5 V $V_{DD} = V_{DDO}$	40			60
$t_{SKEW_{D-D}}$	Device to Device Skew (similar condition) CLK/ $\overline{\text{CLK}}$ to Qx; CLK to Qx			1.0	ns	
$t_{SKEW_{O-O}}$	Output to Output Skew Within A Device		25	100	ps	
$t_S$	Set-up Time to CLK $t_f$	CLK_EN to CLK/CLK	1.0		ns	
		CLK_EN to CLK	0.0			
$t_H$	Hold Time to CLK $t_f$	CLK/ $\overline{\text{CLK}}$ to CLK_EN	0.0		ns	
		CLK to CLK_EN	1.0			
$t_r/t_f$	Output rise and fall times				ns	
		(0.8 V and 2.0 V) 3.3 V $V_{DD} = V_{DDO}$		1.0		
		(0.6 V and 1.8 V) or 3.3 V $V_{DD}$ , 2.5 V $V_{DDO}$		1.0		
	(0.6 V and 1.8 V) 2.5 V $V_{DD} = V_{DDO}$			1.3		

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. Outputs loaded with  $50\ \Omega$  to  $V_{TT}$  ( $V_{DDO}/2$ ); see Figure 5. CLOCK input with 50% duty cycle. Measured at CLK/ $\overline{\text{CLK}}$  crosspoint to Qx  $V_{DDO}/2$ , CLK  $V_{DDO}/2$  to Qx  $V_{DDO}/2$ ; see Figure 4.

# NB3L83948C

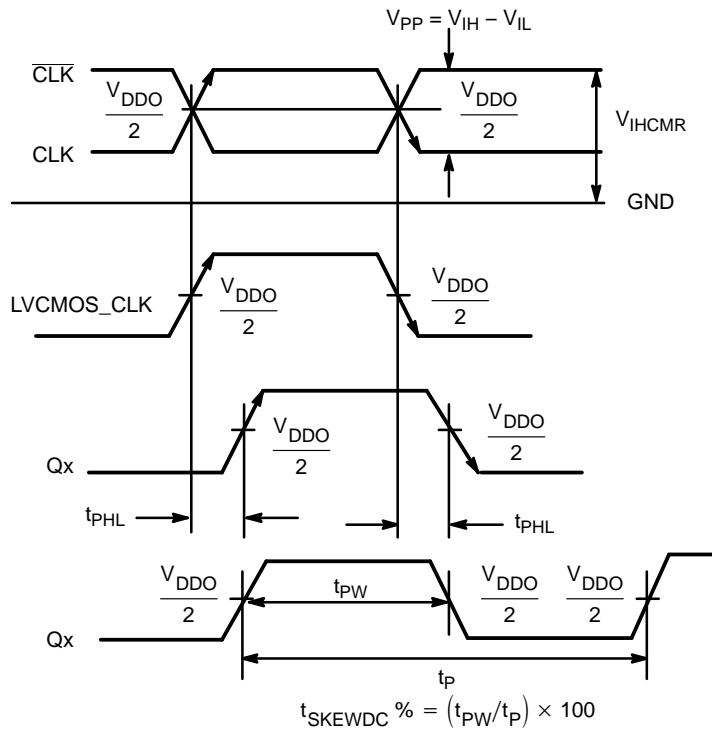


Figure 4. AC Reference Measurement

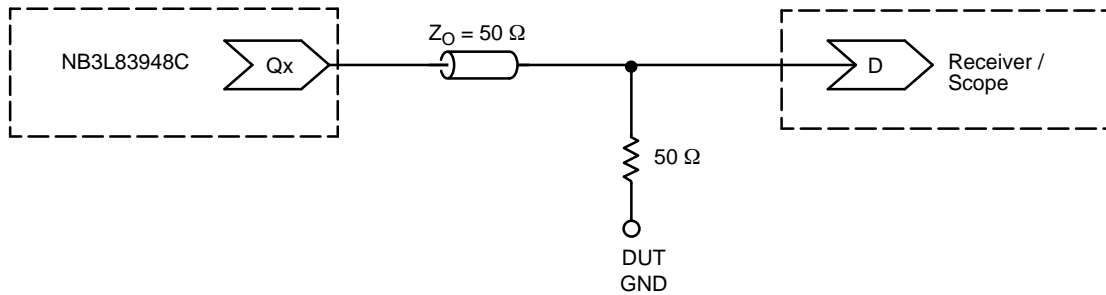


Figure 5. Typical Termination for Output Driver and Device Evaluation. Supplies may be centered on GND ( $\pm 1.65$  V or  $\pm 1.25$  V) to permit direct connection into 50  $\Omega$  to GND Scope modules

## ORDERING INFORMATION

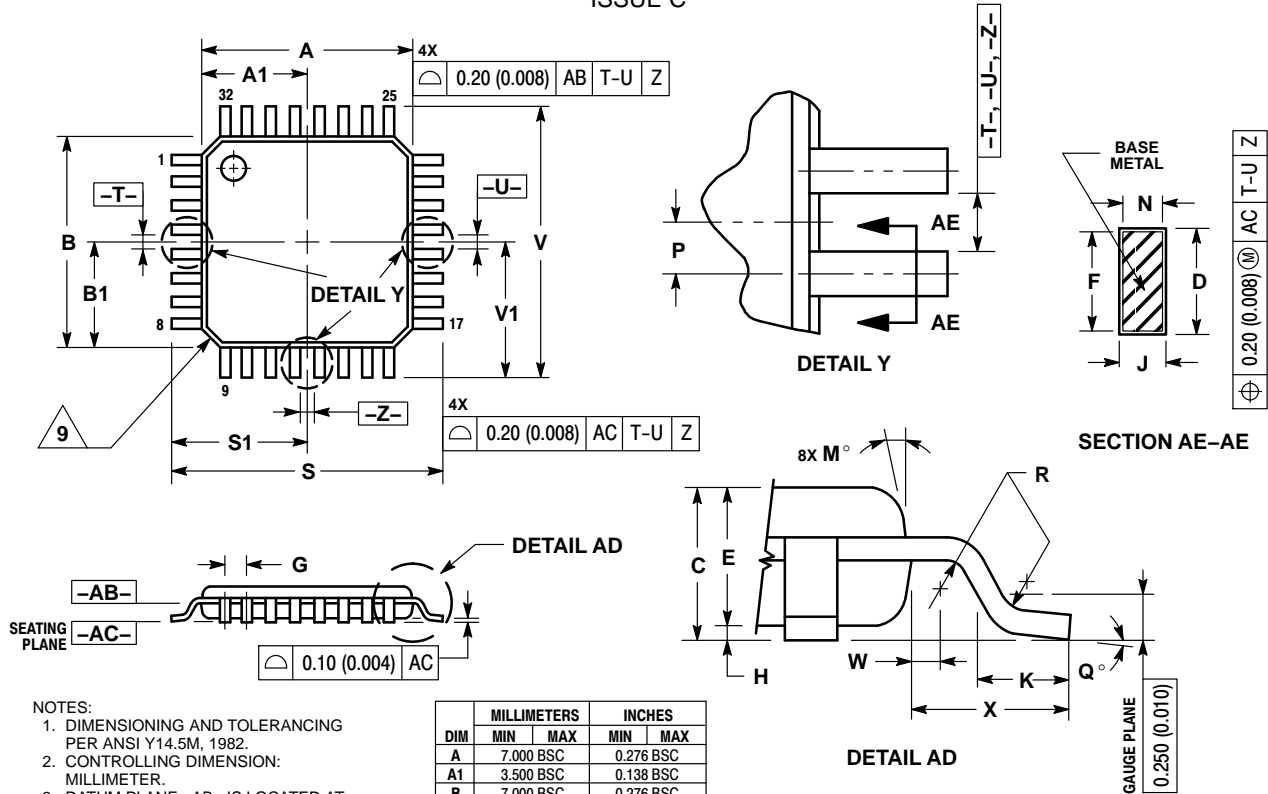
Device	Package	Shipping <sup>†</sup>
NB3L83948CFAG	LQFP-32 (Pb-Free)	250 Units / Tray
NB3L83948CFAR2G	LQFP-32 (Pb-Free)	2000 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NB3L83948C

## PACKAGE DIMENSIONS

32 LEAD LQFP  
CASE 873A-02  
ISSUE C



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.520 (0.020).
8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
9. EXACT SHAPE OF EACH CORNER MAY VARY FROM DEPICTION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	7.000 BSC		0.276 BSC	
A1	3.500 BSC		0.138 BSC	
B	7.000 BSC		0.276 BSC	
B1	3.500 BSC		0.138 BSC	
C	1.400	1.600	0.055	0.063
D	0.300	0.450	0.012	0.018
E	1.350	1.450	0.053	0.057
F	0.300	0.400	0.012	0.016
G	0.800 BSC		0.031 BSC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.450	0.750	0.018	0.030
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.400 BSC		0.016 BSC	
Q	1°	5°	1°	5°
R	0.150	0.250	0.006	0.010
S	9.000 BSC		0.354 BSC	
S1	4.500 BSC		0.177 BSC	
V	9.000 BSC		0.354 BSC	
V1	4.500 BSC		0.177 BSC	
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	

**ON Semiconductor** and **ON** are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

### PUBLICATION ORDERING INFORMATION

**LITERATURE FULFILLMENT:**

Literature Distribution Center for ON Semiconductor  
P.O. Box 5163, Denver, Colorado 80217 USA  
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
Email: orderlit@onsemi.com

**N. American Technical Support:** 800-282-9855 Toll Free USA/Canada  
**Europe, Middle East and Africa Technical Support:** Phone: 421 33 790 2910  
**Japan Customer Focus Center** Phone: 81-3-5817-1050

**ON Semiconductor Website:** [www.onsemi.com](http://www.onsemi.com)  
**Order Literature:** <http://www.onsemi.com/orderlit>  
For additional information, please contact your local Sales Representative

NB3L83948C/D